**IMPORTANT:**

The operating temperature of the Microsemi Adaptec Host Bus Adapter 1000 Series and Host Bus Adapter 1100 Series is 0°C–55°C*, 200LFM. It is essential to provide sufficient airflow to the HBA processor with the adapter installed in a server or PC chassis. A minimum airflow of 200LFM (linear feet per minute) or higher is required for proper functionality.

http://ask.microsemi.com/thermal

*Note: Ambient temperature measured 1 inch (2.54 cm) away from the HBA processor.

**NOTE:**

Please observe best practices for HBA board installation. For example, all drive cabling should be secured to the chassis to prevent the cables from causing the adapter to flex or unseat if the chassis experiences shock.

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